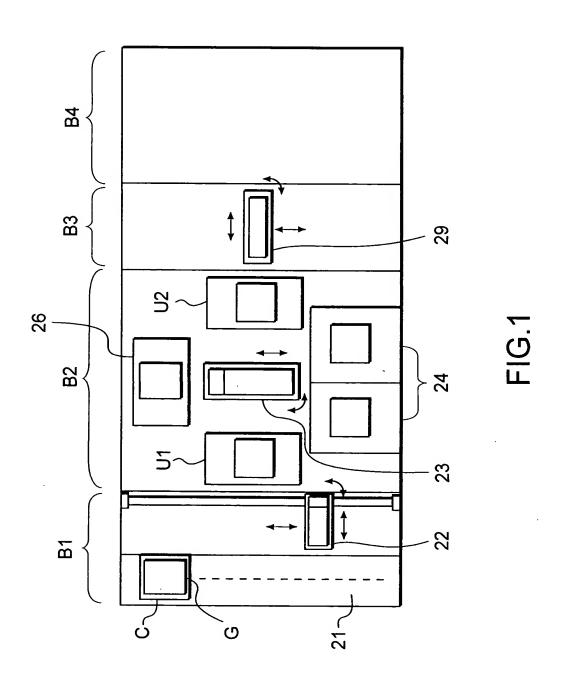
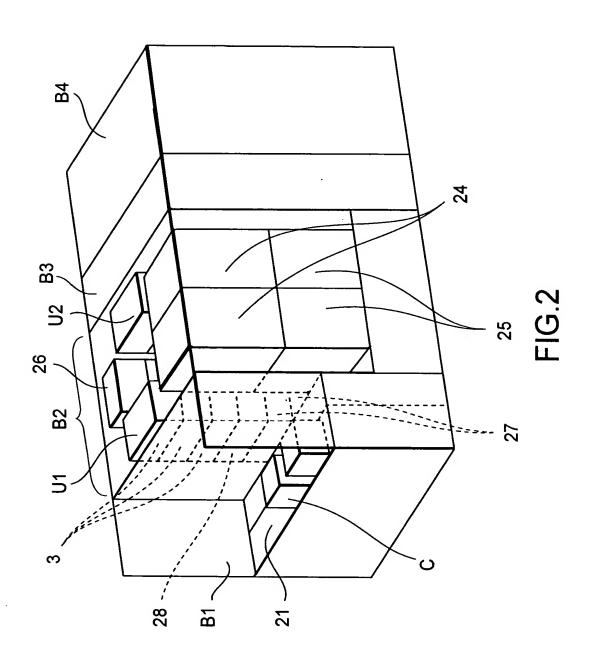
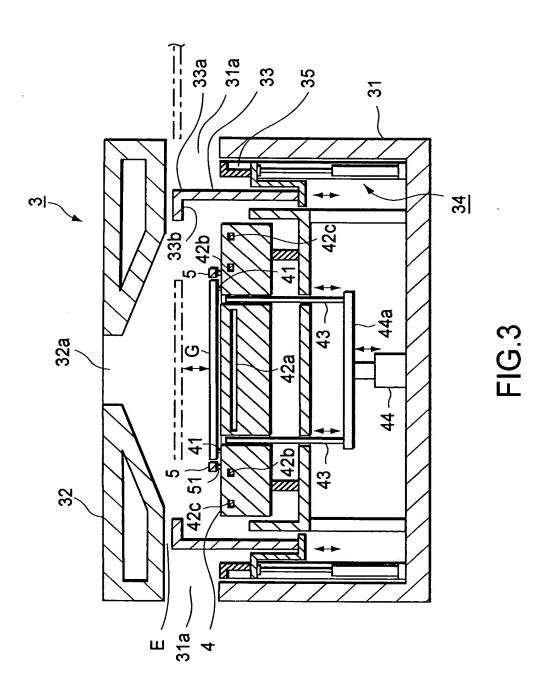
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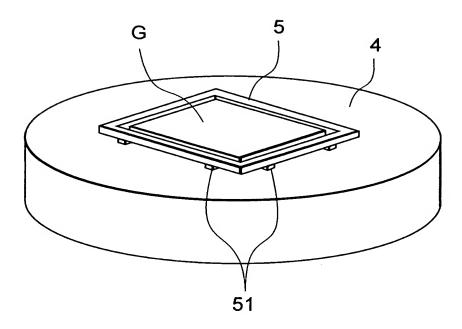


FIG.4

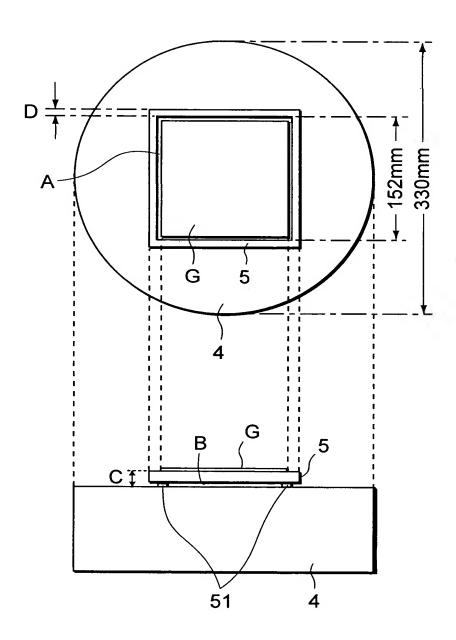


FIG.5

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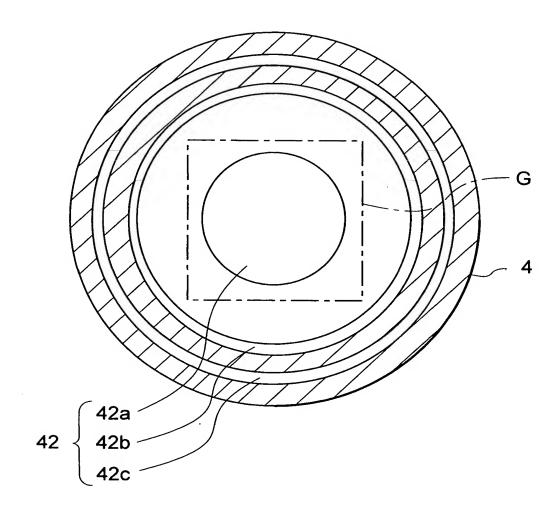


FIG.6

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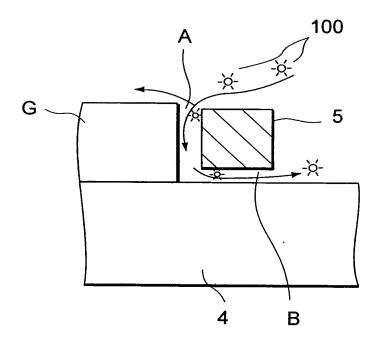


FIG.7

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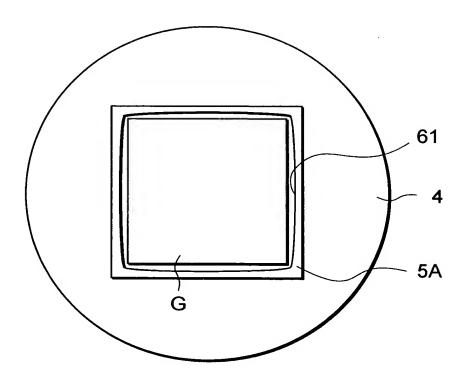


FIG.8A

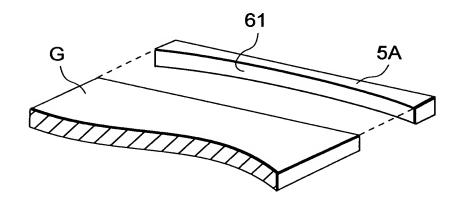


FIG.8B

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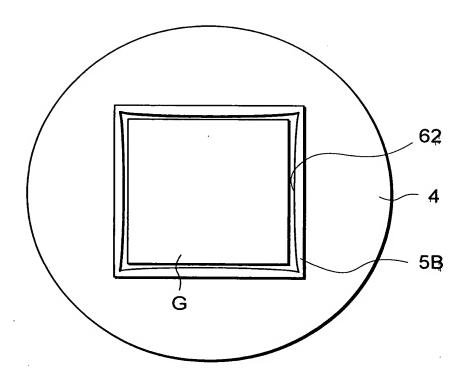


FIG.9A

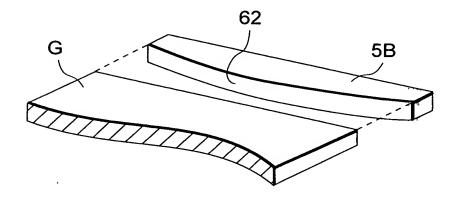


FIG.9B

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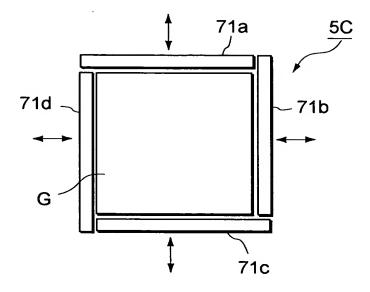


FIG.10A

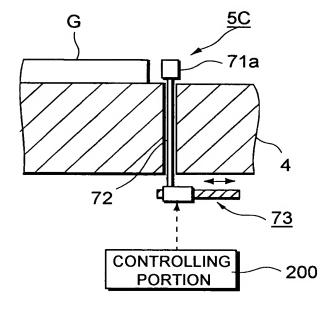


FIG.10B

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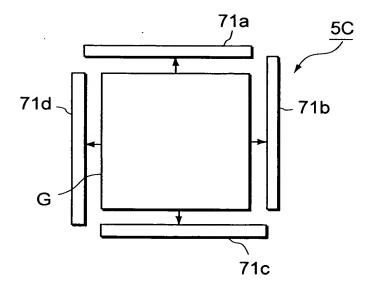


FIG.11A

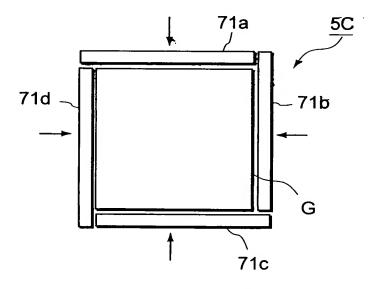


FIG.11B

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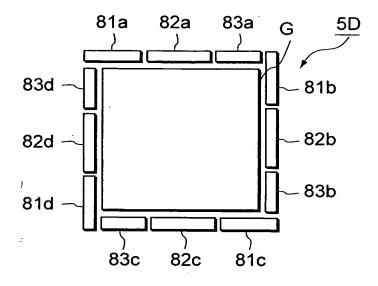


FIG.12A

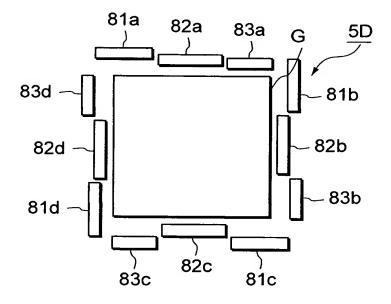


FIG.12B

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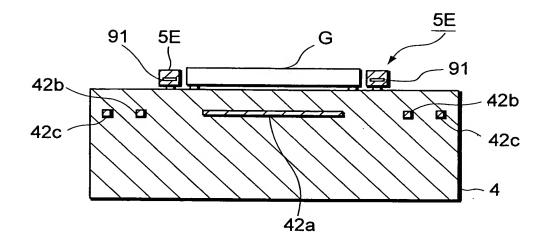
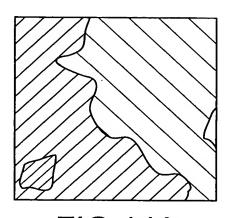


FIG.13

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FIRST EXAMPLE (HEATING PLATE FOR 12-INCH SIZE WAFER, WITH FRAME MEMBER)



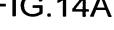
⋙ 120.6 ~ 121℃

120.2 ~ 120.6℃

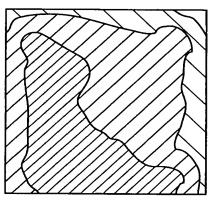
119.8 **~** 120.2℃

119.4 **~** 119.8℃

FIG.14A



FIRST COMPARISON (HEATING PLATE FOR 12-INCH SIZE WAFER, WITHOUT FRAME MEMBER)



119.0 ~ 119.4℃

FIG.14B

SECOND COMPARISON (HEATING PLATE FOR 8-INCH SIZE WAFER, WITHOUT FRAME MEMBER)

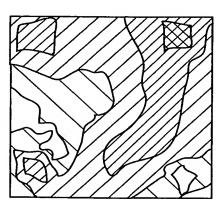


FIG.14C

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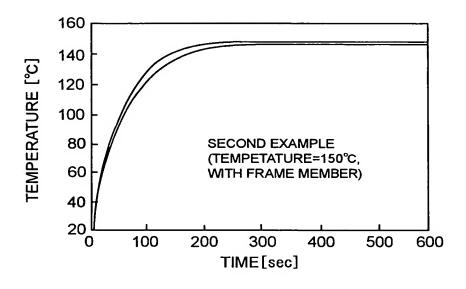


FIG.15A

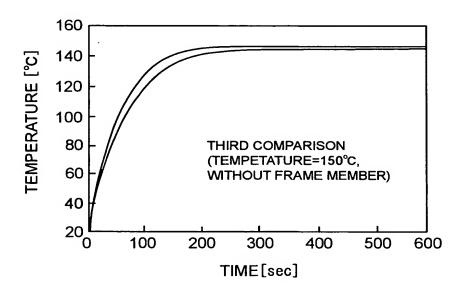


FIG.15B

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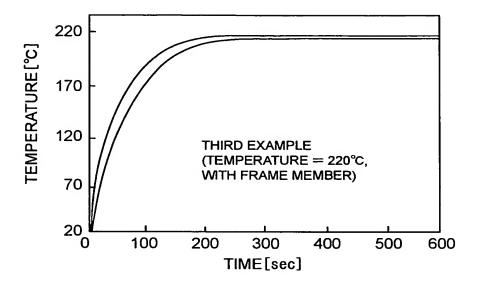


FIG.16A

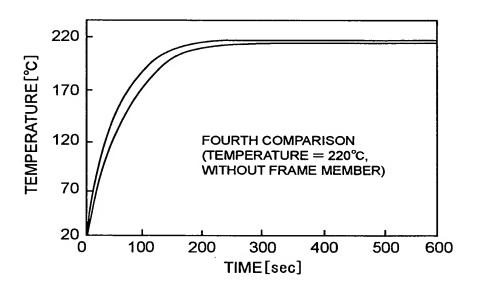


FIG.16B

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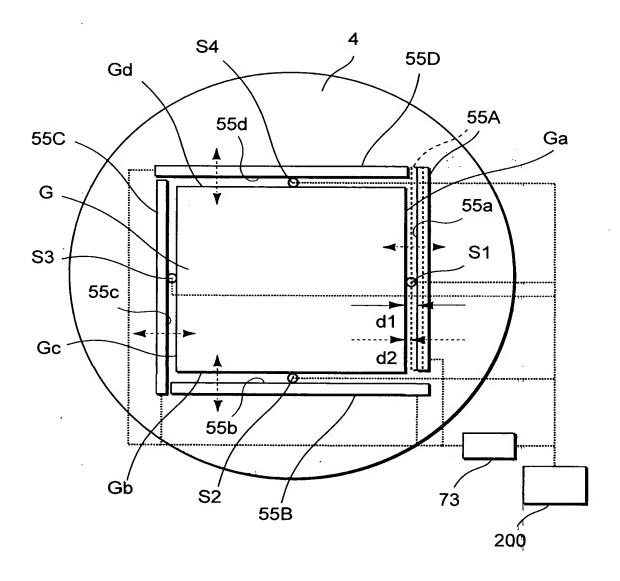


FIG.17

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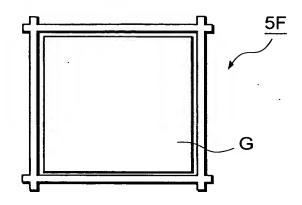


FIG.18A

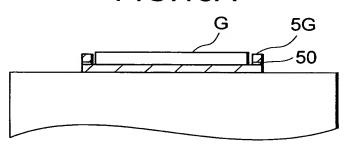


FIG.18B

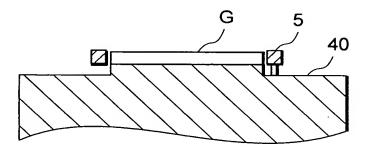


FIG.18C

PRIOR ART

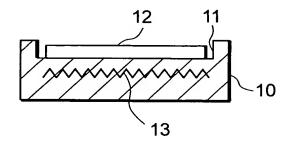


FIG.19

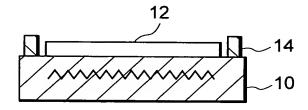


FIG.20

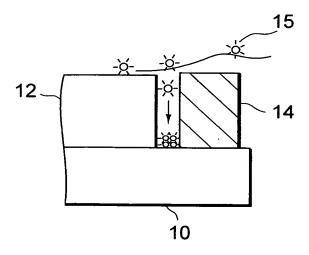


FIG.21